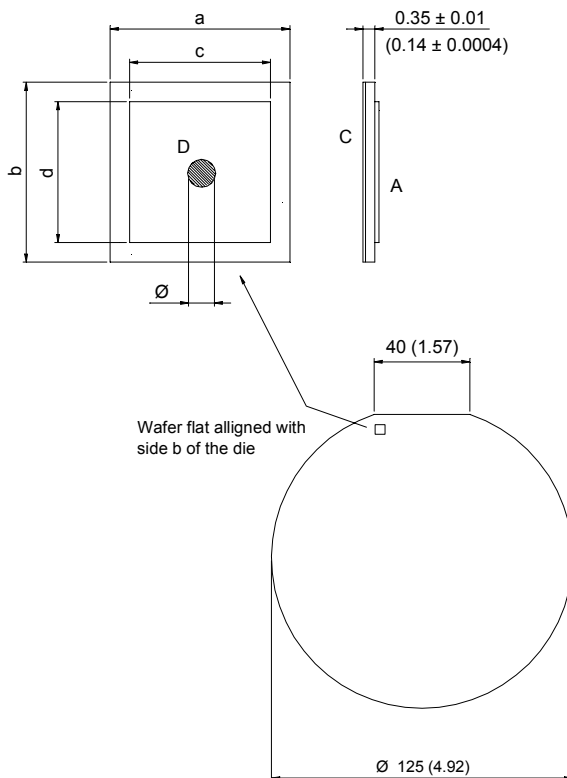


SCHOTTKY DIE 060 x 060 mils



NOTES:

1. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).
2. CONTROLLING DIMENSION: (INCH).
3. DIMENSIONS AND TOLERANCES:
  - $a = 1.52 + 0, - 0.05$   
( $0.060 + 0, - 0.002$ )
  - $b = 1.52 + 0, - 0.05$   
( $0.060 + 0, - 0.002$ )
  - $c = 1.37 + 0, - 0.003$   
( $0.054 + 0, - 0.0001$ )
  - $d = 1.37 + 0, - 0.003$   
( $0.054 + 0, - 0.0001$ )
  - $\varnothing = 0.7 \pm 0.1$   
( $0.03 \pm 0.004$ )
4. LETTER DESIGNATION:
  - A = Anode (Top Metal)
  - C = Cathode (Back Metal)
  - D = Reject Ink Dot (only on non-conforming dies)
5. SAWING:
  - Recommended Blade
  - SEMITEC S1025 QS00 Blade

NOT TO SCALE

**NOTE:** 10 mils die thickness is available on specific request only.  
 Contact factory for information.

## Electrical Characteristics

| Device #     | T <sub>J</sub> Max. (°C) | V <sub>R</sub> (V) | Typ. I <sub>R</sub> @ 25°C (μA) | Typ. I <sub>R</sub> @ 125°C (mA) | Max. V <sub>F</sub> @ I <sub>F</sub> (V) | Package Style |
|--------------|--------------------------|--------------------|---------------------------------|----------------------------------|--|---------------|
| SC060R015x5x | 125                      | 15                 | 800                             | 50                               | 0.35 @ 3A                                | SMC           |
| SC060S020x5x | 150                      | 20                 | n.a. contact factory            |                                  |  |               |
| SC060S030x5x | 150                      | 30                 | 40                              | 15                               | 0.45 @ 3A                                | DPAK(TO-252)  |
| SC060S045x5x | 150                      | 45                 | 30                              | 13                               | 0.53 @ 3A                                | DPAK(TO-252)  |
| SC060S060x5x | 150                      | 60                 | 25                              | 12                               | 0.61 @ 3A                                | DPAK(TO-252)  |
| SC060H045x5x | 175                      | 45                 | n.a. contact factory            |                                  |  |               |
| SC060H100x5x | 175                      | 100                | 2.5                             | 1.5                              | 0.81 @ 3A                                | DPAK(TO-252)  |
| SC060H150x5x | 175                      | 150                | n.a. contact factory            |                                  |  |               |

## Mechanical Data

| Device #     |               | Metal Thickness Front Metal |          |          | Metal Thickness Back Metal |         |         |
|--------------|---------------|-----------------------------|----------|----------|----------------------------|---------|---------|
|              |               |                             |          |          |                            |         |         |
| SC060xxxxA5x | Wire Bondable | –                           | Al 30 kÅ | –        | Cr 1 kÅ                    | Ni 2 kÅ | Ag 3 kÅ |
| SC060xxxxS5x | Solderable    | Ti 2 kÅ                     | Ni 1 kÅ  | Ag 35 kÅ | Cr 1 kÅ                    | Ni 2 kÅ | Ag 3 kÅ |

Recommended Storage Environment: Store in original container, in dessicated nitrogen, with no contamination.

Shelf life for parts stored in above condition is 2 years.

If the storage is done in normal atmosphere shelf life is reduced to six months.

## Packaging

| Device #    | Description                              | Minimum Order Quantity Die in Sale Package |
|-------------|--|--|
| SC060xxxx5B | Inked Probed Unsawn Wafer (Wafer in Box) | 4600                                       |
| SC060xxxx5R | Probed Die in Tape & Reel                | n. a.                                      |
| SC060xxxx5P | Probed Die in Waffle Pack                | n.a.                                       |
| SC060xxxx5F | Inked Probed Sawn Wafer on Film          | 4600                                       |

Ordering Information Table

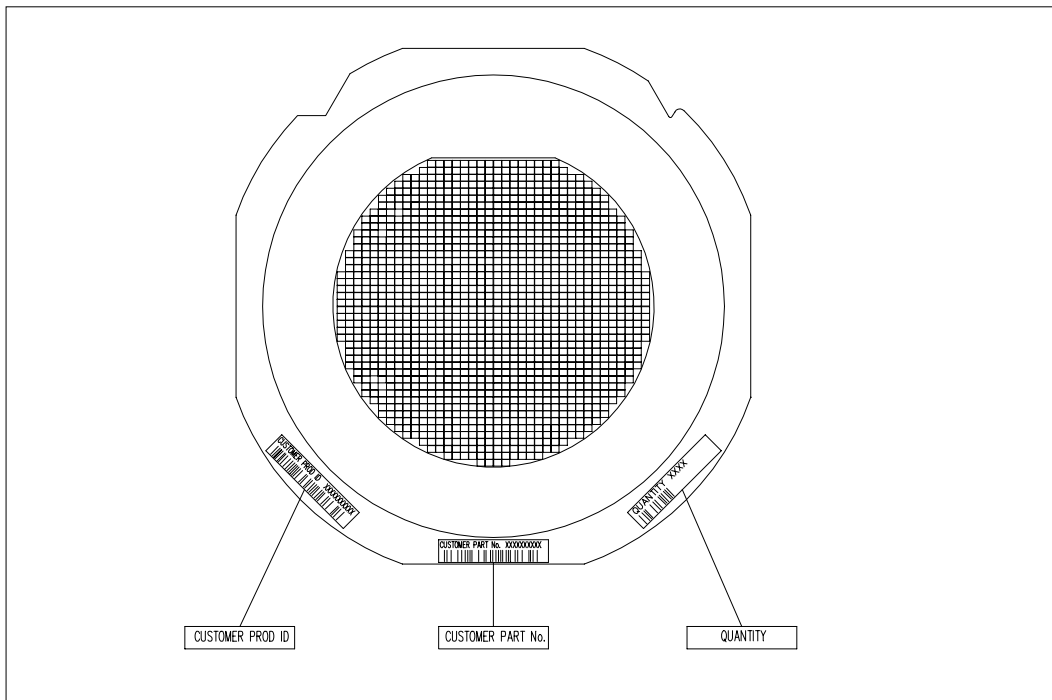
| Device Code |     |   |     |   |   |   |
|-------------|-----|---|-----|---|---|---|
| SC          | 060 | S | 060 | A | 5 | B |
| ①           | ②   | ③ | ④   | ⑤ | ⑥ | ⑦ |

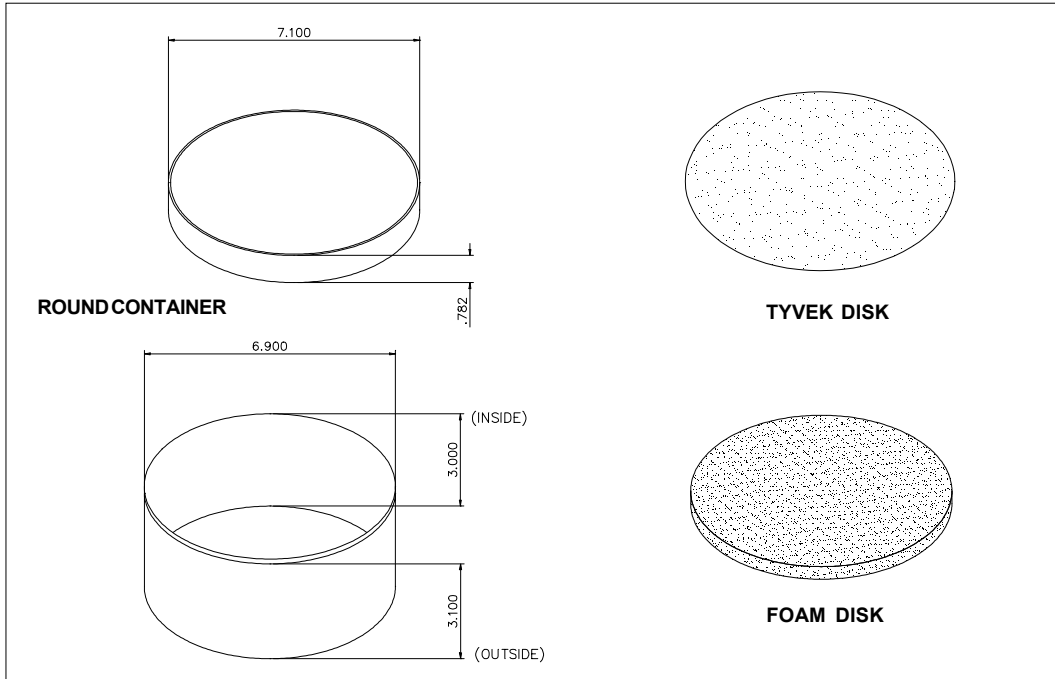
- 1** - Schottky Die
- 2** - Chip Dimension in Mils
- 3** - Process (see Electrical Characteristics Table)
- 4** - Voltage code: Code =  $V_{RRM}$
- 5** - Chip surface metallization (see Mechanical Data Table)
- 6** - Wafer Diameter in inches
- 7** - Packaging (see Packaging Table)

H = 830 Process  
 R = OR'ing Process  
 S = Standard Process

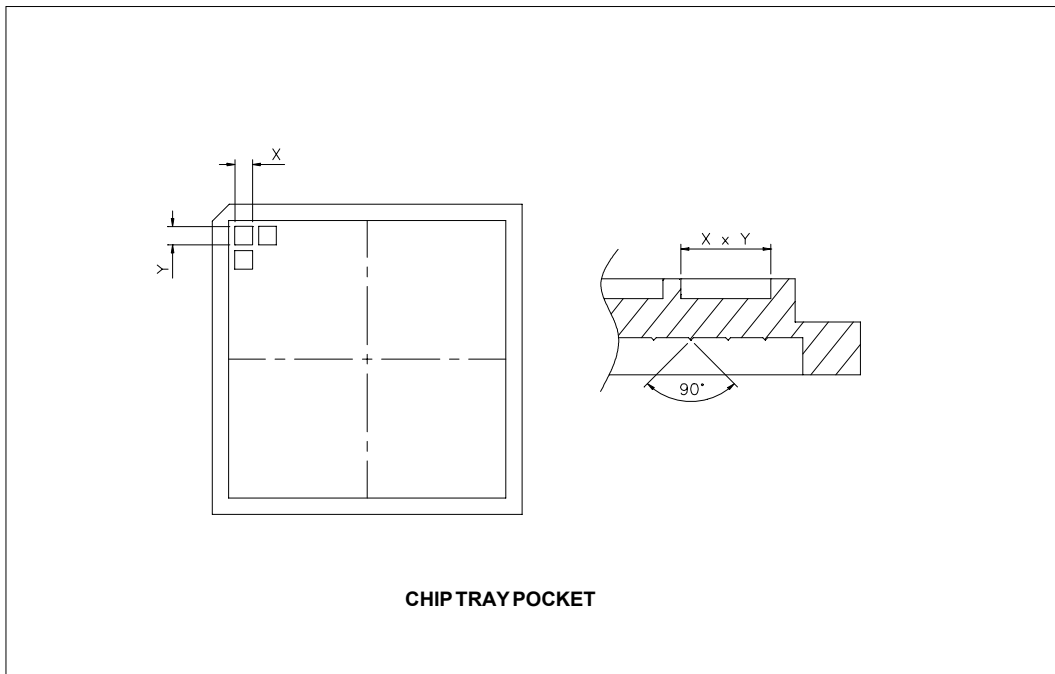
Wafer on Film



Wafer in Box



Die in Waffle Pack



International  
**IOR** Rectifier

**WORLD HEADQUARTERS:** 233 Kansas St., El Segundo, California 90245 U.S.A. Tel: (310) 322 3331. Fax: (310) 322 3332.  
**EUROPEAN HEADQUARTERS:** Hurst Green, Oxted, Surrey RH8 9BB, U.K. Tel: ++ 44 1883 732020. Fax: ++ 44 1883 733408.  
**IR CANADA:** 15 Lincoln Court, Brampton, Markham, Ontario L6T3Z2. Tel: (905) 453 2200. Fax: (905) 475 8801.  
**IR GERMANY:** Saalburgstrasse 157, 61350 Bad Homburg. Tel: ++ 49 6172 96590. Fax: ++ 49 6172 965933.  
**IR ITALY:** Via Liguria 49, 10071 Borgaro, Torino. Tel: ++ 39 11 4510111. Fax: ++ 39 11 4510220.  
**IR FAR EAST:** K&H Bldg., 2F, 30-4 Nishi-Ikebukuro 3-Chome, Toshima-Ku, Tokyo, Japan 171. Tel: 81 3 3983 0086.  
**IR SOUTHEAST ASIA:** 1 Kim Seng Promenade, Great World City West Tower, 13-11, Singapore 237994. Tel: ++ 65 838 4630.  
**IR TAIWAN:** 16 Fl. Suite D.207, Sec. 2, Tun Haw South Road, Taipei, 10673, Taiwan. Tel: 886 2 2377 9936.

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Data and specifications subject to change without notice.